



The European Institute for the PCB Community

## EIPC NEWS

An EIPC Webinar is just like one of our Conference, except that you do not have to travel, you do not have a beer with colleagues, you do not enjoy excellent food, and you do not enjoy convivial company. But we do not live in normal times, and some things are not the same. Manufacturing PCBs, however, remains comfortably complex, and so on.

**The upcoming webinar is on Wednesday 17th February 2021 at 1500 hours CET**

There will be a Q&A session after the last speaker.

For EIPC members the seminar is free of charge; for non-members the fee will be € 50,-.

More information will be available soon.

To register online, please go to [www.eipc.org](http://www.eipc.org)



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Issue 3 – January 2021*

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### NEWS FROM BELGIUM

#### Elsyca appoints Marc Boonen as Chief Commercial Officer

Elsyca, the global leader in electrochemical intelligence, announces the appointment of Mr. Marc Boonen as Chief Commercial Officer from February 1st and he will be responsible for the business expansion strategy and will assume the operational leadership of the global sales & marketing team.

Jean-Marc Dewilde, Managing Director of Elsyca, said: “Marc is a great addition to the Elsyca team and we are very excited about the experience he brings in expanding and developing high performance sales organizations. His joining continues our momentum on international growth over the next years. The addition of Marc to the Elsyca team is yet another and very exciting milestone in Elsyca’s continued mission to provide breakthrough solutions that deliver real returns on investment”.

Marc is a highly accomplished manager with over 30 years’ experience in advanced technology solution companies supporting engineering, logistics, and production departments in automotive, aerospace, electronics, oil & gas, consumer goods, and many other industries. Marc holds a degree in Engineering (electro mechanics) and has completed multiple management and leadership programs.

#### **About Elsyca**

*Headquartered in Belgium, Elsyca is a software company and global leader in electrochemical intelligence for many clients across the globe.*

*Elsyca (www.elsyca.com) is the engineering innovation partner of choice for corrosion engineering and corrosion resistant design, cathodic protection & AC mitigation, as well as for surface finishing and electrochemical manufacturing. With a powerful combination of a unique computer simulation technology and practical engineering skills, Elsyca is capable of designing, modelling, simulating and optimizing the complete range of electrochemical processes.*

For more information please contact the Elsyca team:

[info@elsyca.com](mailto:info@elsyca.com)



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### NEWS FROM THE FED

<https://www.fed.de/>

In February we are offering a whole range of online training courses from the world of electronics.

Find the right topic and educate yourself. We look forward to your registration.

25.01. - 01.02. : Online seminar "IPC-A-610 G course for specialists" (Thomas Lauer)

08.02. - 09.02. : Online seminar "IPC-A-610: Accompanying aspects and processes" (Thomas Lauer)

08.02. - 15.02. : Online seminar "IPC-A-610 G course for specialists" (Peter Koller)

02/15 - 19.02. : Online seminar "High-speed assembly design" (Friedbert Hillebrand)

02/18 - 19.02. : Online seminar "ESD protection management basics" (Michael Günther)

Information on the individual training courses can be found under the link provided or at the bottom of the newsletter. Additional online courses and face-to-face seminars can be found on the FED website.

February 15-19, 2021 - Online - FED

Online seminar: "High-speed assembly design"

Speaker Friedbert Hillebrand teaches the participants in the online seminar "High-Speed Module Design" on five mornings how to create optimal circuit and printed circuit board designs for high-speed applications, taking into account signal integrity and EMC. The different design strategies are explained and presented with the help of simulation tools. A slideshow of the seminar and the content can be found here. At the end of the seminar, the ZED Level IV exam can be taken online. All participants receive extensive digital training documents and a participant certificate.

Information and registration 01/28/2021 - Online - FED

RG Berlin: Which selective soldering process is the right one?

On January 28th at 10 am, the Berlin regional group will present the topic "Which selective soldering process is the right one? - Part 2" in an online lecture. The speaker is Manfred Fehrenbach, EUTECH GmbH. The online lecture invites you to understand the essential principles of selective soldering process selection. It shows which parameters, conditions and specialties must be taken into account in order to obtain an efficient, reproducible soldering process that is perfectly tailored to the end product. Because both the actual soldering process and the layout geometry of the assembly, the pin-pad component geometries and the wetting-friendly metallization of all components involved influence the final soldering result.

02/03/2021 - Online - FED

RG Stuttgart: Live session "X-ray analysis"

The next online lecture of the Stuttgart regional group from the online series "Kurz & crisp" will take place on February 3rd at 4 pm. It is the 11th part of this series on current topics from electronics - this time on the topic of "X-ray analysis". The speaker is Uwe Hartnagel, XRAY-LAB GmbH & Co. KG. This online session consists of a practical part with handling of the samples and a presentation part. The practical part will be broadcast live from production.



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### NEWS FROM THE UK

#### Proceedings Now Available

#### Future Horizons' Annual SC Industry Outlook

The full IFS2021 seminar proceedings (185 slides) are now available for purchase, either [call](tel:+441732740440) (+44 1732 740440), e-mail ([mail@futurehorizons.com](mailto:mail@futurehorizons.com)), fax (+44 1732 608045), on-line ([www.futurehorizons.com](http://www.futurehorizons.com)) or by post (Blakes Green Cottage, Sevenoaks, Kent TN15 0LQ, England).

Find out the reasons behind our 18 percent growth forecast for 2021; why we believe its stormy weather ahead for the automotive industry incumbents and why the current component shortages are here for the rest of the year, possibly longer.

Our industry forecasts, methodology and analyses have proved both accurate and insightful, and this year will prove no exception. We were the only analyst who forecast still positive industry growth for 2020 when all others were predicting the Coronavirus pandemic with send semiconductor market negative.

This year's slide set, explained why we were right and willing to stick our necks out and go against the tide.

Priced at only UK£195, pre-payment by Bank transfer, PO number or via PayPal (please specify preference). Site licence for corporate library or multi- use within your organisation, is also available at UK£595. Seminar proceedings are UK VAT zero rated.

Sincerely

Malcolm Penn  
Chairman & CEO



## "Semiconductor Packaging Workshop"

"Learn How to Package Electronic Devices - Right First Time"

**Thursday 11 February 2021: 10:00 - 16:00**

This **Online Workshop** provides training on the wide range of **packaging technologies** for the **design, manufacture and test of electronic products**. It will also serve as a refresher for those who wish to expand the breadth of their knowledge in:

- Die Preparation, Attach and Interconnection Techniques
- Package, Substrate and Encapsulation Options
- Modelling and Simulation
- Test, Inspection and Reliability (including demonstrations of bond testing and X-Ray Inspection)

*Register below for this event.*

[Register Here](#)

### **Forthcoming IMAPS-UK Online Events**

Please Click on the Links below for More Information

[MicroTech 2021 Online Conference - 25 March 2021](#)

Heterogeneous Integration - Packaging Future Microsystems



For any other details or information please contact:

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### ELECTRONICS INDUSTRY NEWS

## To Close the Digital Divide, the FCC Must Redefine Broadband Speeds

*Dating from 2015, the agency's definition of broadband is much too slow*

By [Stacey Higginbotham](#)

The coronavirus pandemic has brought the broadband gap in the United States into stark relief—5.6 percent of the population has no access to broadband infrastructure. But for an even larger percentage of the population, the issue is that they can't afford access, or they get by on mobile phone plans. Recent estimates, for example, suggest that 15 million to 16 million students—roughly 30 percent of the grade-school population in the United States—lack broadband access for some reason.

The Federal Communications Commission (FCC) has punted on broadband access for at least a decade. With the recent change in the regulatory regime, it's time for the country that created the ARPANET to fix its broadband access problem. While the lack of access is driven largely by broadband's high cost, the reason that cost is driving the broadband gap is because the FCC's current definition of broadband is stuck in the early 2000s.

The FCC defines broadband as a download speed of 25 megabits per second and an upload speed of 3 Mb/s. The agency set this definition in 2015, when it was already immediately outdated. At that time, I was already stressing a 50 Mb/s connection just from a couple of Netflix streams and working from home. Before 2015, the defined broadband speeds in the United States were an anemic 4 Mb/s down and 1 Mb/s up, set in 2010.

If the FCC wants to address the broadband gap rather than placate the telephone companies it's supposed to regulate, it should again redefine broadband. The FCC could easily establish broadband as 100 Mb/s down and at least 10 Mb/s up. This isn't a radical proposal: As of 2018, 90.5 percent of the U.S. population already had access to 100 Mb/s speeds, but only

45.7 percent were tapping into it, according to the FCC's 2020 Broadband Deployment Report.

Redefining broadband will force upgrades where necessary and also reveal locations where competition is low and prices are high. As things stand, most people in need of speeds above 100 Mb/s have only one option: cable providers. Fiber is an alternative, but most U.S. fiber deployments are in wealthy suburban and dense urban areas, leaving rural students and those living on reservations behind. A lack of competition leaves cable providers able to impose data caps and raise fees.

What seems like a lack of demand is more likely a rejection of a high-cost service, even as more people require 100 Mb/s for their broadband needs. In the United States, 100 Mb/s plans cost \$81.19 per month on average, according to data from consumer interest group New America. The group gathered broadband prices across 760 plans in 28 cities around the world, including 14 cities in the United States. When compared with other countries, prices in the United States are much higher. In Europe, the average cost of a 100/10 Mb/s plan is \$48.48, and in Asia, a similar plan would cost \$69.76.

Closing the broadband gap will still require more infrastructure and fewer monopolies, but redefining broadband is a start. With a new understanding of what constitutes reasonable broadband, the United States can proactively create new policies that promote the rollout of plans that will meet the needs of today and the future.

*This article appears in the February 2021 print issue as "Redefining Broadband."*



Issue 3 - January 2021

NEWS FROM THE IPC

**Futurist, Writer and Manufacturing Tech Expert Travis Hessman to Keynote IPC APEX EXPO 2021**

**BANNOCKBURN, Ill., USA, January 18, 2021** — Each year, [IPC APEX EXPO](#) features industry’s most dynamic, innovative minds to deliver keynote presentations that are both educational and entertaining. IPC APEX EXPO 2021 will feature *IndustryWeek* Editor-in-Chief Travis Hessman. During his keynote on March 10, Hessman will present, “The Great Digital Transformation.”

Hessman will educate keynote participants on the process undertaken by some of today’s most successful companies and what they are doing to transform a dizzying array of technologies such as connected machine-to-machine systems, machine learning and artificial intelligence into actionable, effective digital strategies. In addition, he will cover how they achieved greater operational efficiency and launched new products faster while improving product quality across their businesses.

Guided by Hessman, participants will navigate a roadmap to digital transformation that can help move their companies from the sidelines to the heart of the Factory of the Future -- The Industry 4.0 revolution.

As chief editor of *IndustryWeek*, Hessman offers a unique perspective on the digital manufacturing revolution as he is in daily contact with some of the world’s most successful and innovative manufacturers who are immersed in real-life implementation, application, and strategies for digital transformation success. His presentation will mix these perspectives with his

background as a teacher, a mentor, and a writer to create a powerful storytelling experience that crafts a distinct narrative to help cut through the noise and hype and drive real progress for the industry. Later in the afternoon, Hessman will conduct a live, one-hour Q&A session with attendees who will have the opportunity to pose their own questions on digital transformation.

Hessman's keynote is free to all IPC APEX EXPO participants. In addition to Hessman's keynote, John Mitchell, IPC president and CEO and Shawn DuBravac, IPC chief economist, will deliver keynotes on March 8 and 11, respectively. The virtual conference, courses and online exhibition will run March 8–12, 2021. For more information on schedule and registration options, visit [www.IPCAPEXEXPO.org](http://www.IPCAPEXEXPO.org).



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## International Diary

### 2021

#### **IPC APEX EXPO goes virtual**

March

#### **EIPC @ SMTconnect**

May 4-6

Nuremberg, Germany

#### **5<sup>th</sup> EIPC Technical Snapshot Webinar**

Registrations via [www.eipc.org](http://www.eipc.org)

February 17